

1. (Amended) An integrated circuit package, comprising:
  - a) a pattern of contact pads applied to a surface of the integrated circuit package;
  - b) a number of annular ring shaped alignment pads applied to said surface at known locations with respect to said pattern of contact pads; and
  - c) a number of alignment balls attached to said number of annular ring shaped alignment pads.
7. (Amended) An integrated circuit package as in claim 1, wherein at least one of said number of alignment balls is hard enough to resist deformation as said integrated circuit package is aligned with an interface.
8. (Amended) An integrated circuit package as in claim 1, wherein diameters of said number of annular ring shaped alignment pads are smaller than diameters of said number of alignment balls.
9. (Amended) An integrated circuit package as in claim 1, further comprising a wetting media that attaches said number of alignment balls to said number of annular ring shaped alignment pads.
11. (Amended) An integrated circuit package as in claim 1, wherein said pattern of contact pads forms a land grid array, wherein said number of annular ring shaped alignment pads is three, and wherein said alignment balls are hard enough to resist deformation as said integrated circuit package is aligned with an interface; said integrated circuit package further comprising a wetting media that attaches said number of alignment balls to said number of annular ring shaped alignment pads.
13. (Amended) An integrated circuit package, comprising:
  - a) a pattern of contact pads applied to a surface of the integrated circuit package;
  - b) a number of annular ring shaped alignment pads applied to said

surface at known locations with respect to said pattern of contact pads;  
and

- c) a number of alignment bullets attached to said number of annular ring shaped alignment pads.

16. (Amended) An integrated circuit package as in claim 13, wherein said number of alignment pads is three.

17. (Amended) An integrated circuit package as in claim 13, further comprising a wetting media that attaches said number of alignment bullets to said number of annular ring shaped alignment pads.

18. (Amended) An integrated circuit package as in claim 13, wherein said pattern of contact pads forms a land grid array, wherein said number of alignment bullets is three, and wherein said alignment bullets are hard enough to resist deformation as said integrated circuit package is aligned with an interface; said integrated circuit package further comprising a wetting media that attaches said number of alignment bullets to said number of annular ring shaped alignment pads.

26. (Amended) An integrated circuit package, comprising:

- a) electrical contact means applied to a surface of the integrated circuit package;
- b) a number of annular ring shaped alignment means applied to said surface at known locations with respect to said electrical contact means; and
- c) a number of alignment balls attached to said number of annular ring shaped alignment pads.

27. (Amended) An integrated circuit package, comprising:

- a) electrical contact means applied to a surface of the integrated circuit package;

- b) a number of annular ring shaped alignment means applied to said surface at known locations with respect to said electrical contact means; and
- c) a number of bullet shaped alignment means attached to said number of annular ring shaped alignment pads.

Please add the following new claims:

28. (New) An integrated circuit package as in claim 13, wherein at least one of said number of alignment bullets has an end which is shaped to protrude into one of said number of annular ring shaped alignment pads.

29. (New) An integrated circuit package as in claim 28, wherein said end of said at least one alignment bullet comprises a raised disc.

**In the Drawings:**

A proposed amendment to FIG. 5 is submitted herewith under separate cover letter to the Official Draftsperson. The amendment adds an alignment pad 504.